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Diodes Incorporated

PERICOM®

PI6C20400

1:4 Clock Driver for Intel PCI Express Chipsets

Features

→ Four Pairs of Differential Clocks
→ Low skew < 50ps
→ Low jitter < 50ps
→ Output Enable for all outputs
→ Outputs tristate control via SMBus
→ Power Management Control
→ Programmable PLL Bandwidth
→ PLL or Fanout operation
→ 3.3V Operation
→ Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
→ Halogen and Antimony Free. "Green" Device (Note 3)
→ For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative.
   https://www.diodes.com/quality/product-definitions/
→ Packaging (Pb-free and Green):
   • 28-Pin TSSOP (L28)

Description

The PI6C20400 is a high-speed, low-noise differential clock buffer designed to be companion to PI6C410B. The device distributes the differential SRC clock from PI6C410B to four differential pairs of clock outputs either with or without PLL. The clock outputs are controlled by input selection of SRC_STOP#, PWRDWN# and SMBus, SCLK and SDA. When input of either SRC_STOP# or PWRDWN# is low, the output clocks are Tristated. When PWRDWN# is low, the SDA and SCLK inputs must be Tri-stated.
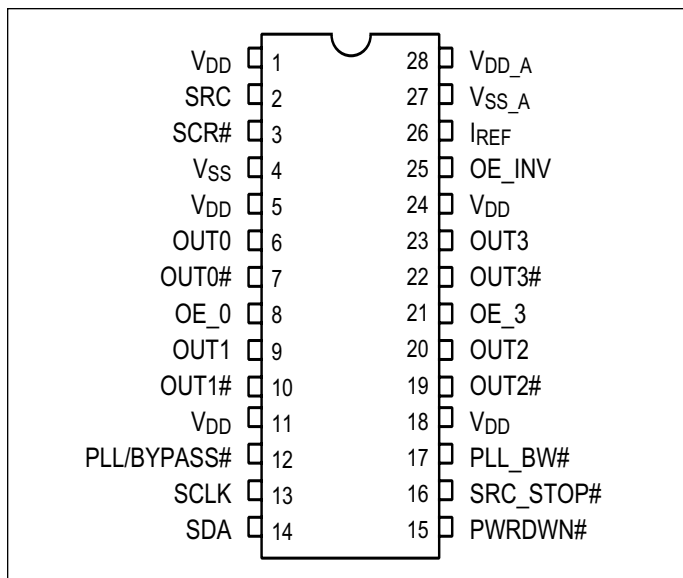
Block Diagram
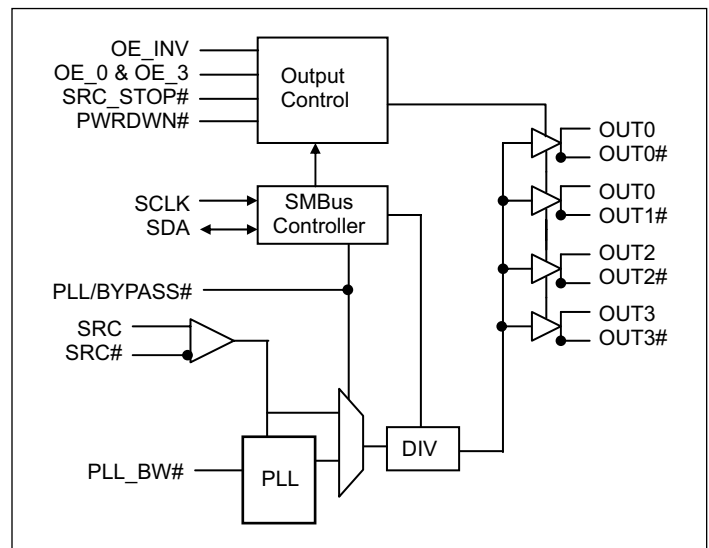
Notes:

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

Pin Configuration

```
           ┌───────∩───────┐
    V_DD ──┤ 1          28 ├── V_DD_A
     SRC ──┤ 2          27 ├── V_SS_A
    SCR# ──┤ 3          26 ├── I_REF
     V_SS ─┤ 4          25 ├── OE_INV
    V_DD ──┤ 5          24 ├── V_DD
    OUT0 ──┤ 6          23 ├── OUT3
   OUT0# ──┤ 7          22 ├── OUT3#
    OE_0 ──┤ 8          21 ├── OE_3
    OUT1 ──┤ 9          20 ├── OUT2
   OUT1# ──┤ 10         19 ├── OUT2#
    V_DD ──┤ 11         18 ├── V_DD
PLL/BYPASS# ┤ 12        17 ├── PLL_BW#
    SCLK ──┤ 13         16 ├── SRC_STOP#
     SDA ──┤ 14         15 ├── PWRDWN#
           └───────────────┘
```

Pin Descriptions

Pin#	Pin Name	Type	Description
2, 3	SRC & SRC#	Input	0.7V Differential SRC input from PI6C410 clock synthesizer
8, 21	OE_0 & OE_3	Input	3.3V LVTTL input for enabling outputs, active high. OE_0 for OUT0 / OUT0# OE_3 for OUT3 / OUT3#
25	OE_INV	Input	3.3V LVTTL input for inverting the OE, SRC_STOP# and PWRDWN# pins. When 0 = same stage When 1 = OE_0, OE_3, SRC_STOP#, PWRDWN# inverted.
6, 7, 9, 10, 19, 20, 22, 23	OUT[0:3] & OUT[0:3]#	Output	0.7V Differential outputs
12	PLL/BYPASS#	Input	3.3V LVTTL input for selecting fan-out of PLL operation.
13	SCLK	Input	SMBus compatible SCLOCK input
14	SDA	I/O	SMBus compatible SDATA
26	IREF	Input	External resistor connection to set the differential output current
16	SRC_STOP#	Input	3.3V LVTTL input for SRC stop, active low
17	PLL_BW#	Input	3.3V LVTTL input for selecting the PLL bandwidth
15	PWRDWN#	Input	3.3V LVTTL input for Power Down operation, active low
1, 5, 11, 18, 24	V_DD	Power	3.3V Power Supply for Outputs
4	VSS	Ground	Ground for Outputs
27	VSS_A	Ground	Ground for PLL
28	VDD_A	Power	3.3V Power Supply for PLL

Serial Data Interface (SMBus)

This part is a slave only SMBus device that supports indexed block read and indexed block write protocol using a single 7-bit address and read/write bit as shown below.

Address Assignment

A6	A5	A4	A3	A2	A1	A0	W/R
1	1	0	1	1	1	0	0/1

Data Protocol

1 bit	7 bits	1	1	8 bits	1	8 bits	1	8 bits	1		8 bits	1	1 bit
Start bit	Slave Addr	R/W	Ack	Register offset	Ack	Byte Count = N	Ack	Data Byte 0	Ack	…	Data Byte N - 1	Ack	Stop bit

Notes:

1. Register offset for indicating the starting register for indexed block write and indexed block read. Byte Count in write mode cannot be 0.

Data Byte 0: Control Register

Bit	Descriptions	Type	Power Up Condition	Output(s) Affected	Source Pin
0	Outputs Mode 0 = Divide by 2 1 = Normal	RW	1 = Normal	OUT[0:3], OUT[0:3]#	NA
1	PLL/BYPASS# 0 = Fanout 1 = PLL	RW	1 = PLL	OUT[0:3], OUT[0:3]#	NA
2	PLL Bandwidth 0 = High Bandwidth, 1 = Low Bandwidth	RW	1 = Low	OUT[0:3], OUT[0:3]#	NA
3	Reserved				NA
4	Reserved				NA
5	Reserved				NA
6	SRC_STOP# 0 = Driven when stopped 1 = Tristate	RW	0 = Driven when stopped	OUT[0:3], OUT[0:3]#	
7	PWRDWN# 0 = Driven when stopped 1 = Tristate	RW	0 = Driven when stopped	OUT[0:3], OUT[0:3]#	NA

Data Byte 1: Control Register

Bit	Descriptions	Type	Power Up Condition	Output(s) Affected	Source Pin
0					
1	OUTPUTS enable	RW	1 = Enabled	OUT0, OUT0#	NA
2	1 = Enabled 0 = Disabled	RW	1 = Enabled	OUT1, OUT1#	NA
3					
4					
5	OUTPUTS enable	RW	1 = Enabled	OUT2, OUT2#	NA
6	1 = Enabled 0 = Disabled	RW	1 = Enabled	OUT3, OUT3#	NA
7					

Data Byte 2: Control Register

Bit	Descriptions	Type	Power Up Condition	Output(s) Affected	Source Pin
0					
1	Allow control of OUTPUTS with assertion of SRC_STOP#	RW	0 = Free running	OUT0, OUT0#	NA
2	0 = Free running 1 = Stopped with SRC_Stop#	RW	0 = Free running	OUT1, OUT1#	NA
3					
4					
5	Allow control of OUTPUTS with assertion of SRC_STOP#	RW	0 = Free running	OUT2, OUT2#	NA
6	0 = Free running 1 = Stopped with SRC_Stop#	RW	0 = Free running	OUT3, OUT3#	NA
7					

Data Byte 3: Control Register

Bit	Descriptions	Type	Power Up Condition	Output(s) Affected	Source Pin
0		RW			
1		RW			
2		RW			
3	Reserved	RW			
4		RW			
5		RW			
6		RW			
7		RW			

Data Byte 4: Pericom ID Register

Bit	Descriptions	Type	Power Up Condition	Output(s) Affected	Pin
0		R	0	NA	NA
1		R	0	NA	NA
2		R	0	NA	NA
3	Pericom ID	R	0	NA	NA
4		R	0	NA	NA
5		R	1	NA	NA
6		R	0	NA	NA
7		R	0	NA	NA

Functionality

PWRDWN#	OUT	OUT#	SRC_Stop#	OUT	OUT#
1	Normal	Normal	1	Normal	Normal
0	$I_{REF} \times 2$ or Float	Low	0	$I_{REF} \times 6$ or Float	Low

Power Down (PWRDWN# assertion)
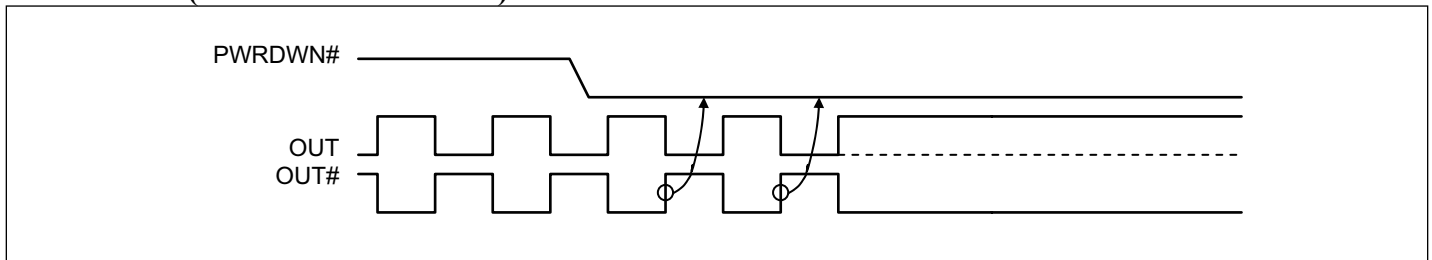
Figure 1. Power Down Sequence

Power Down (PWRDWN# De-assertion)
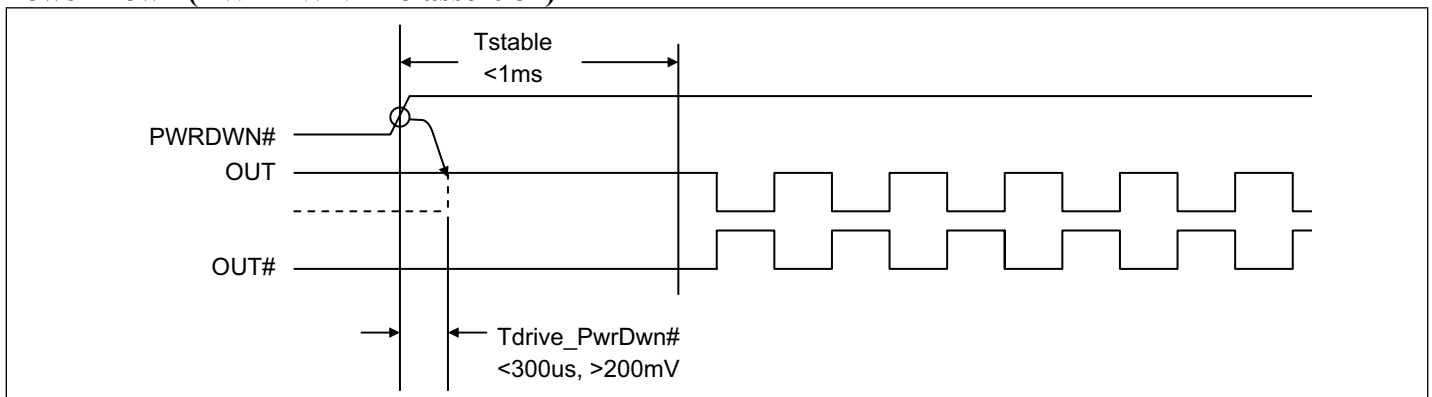
Figure 2. Power Down De-assert Sequence

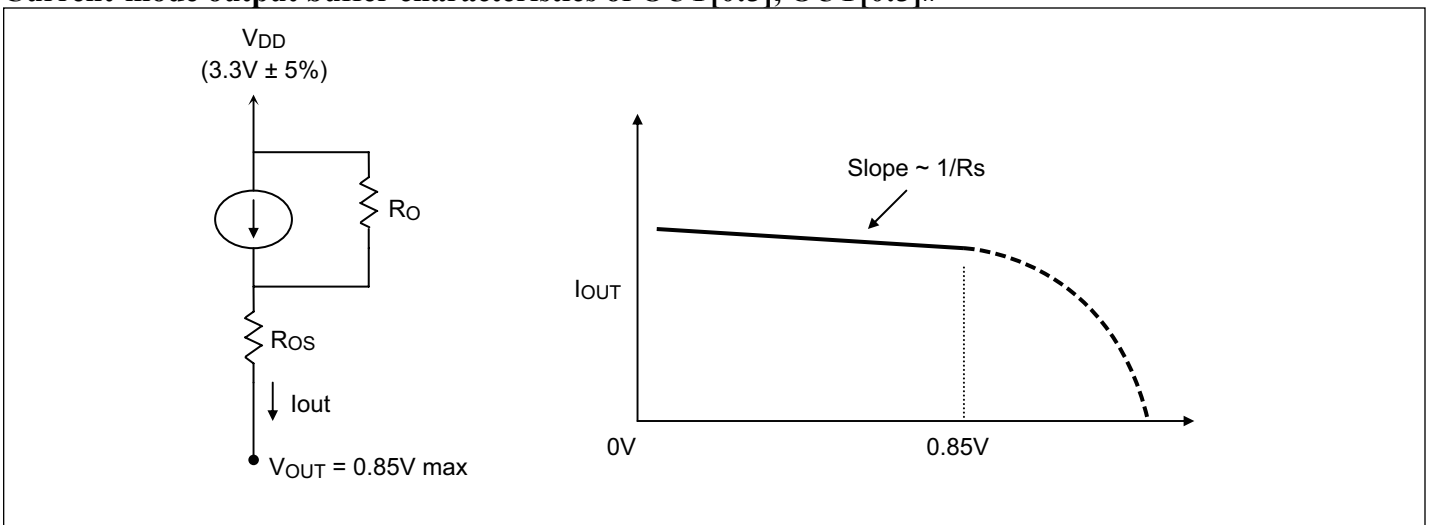## Current-mode output buffer characteristics of OUT[0:3], OUT[0:3]#

Figure 3. Simplified Diagram of Current-mode Output Buffer

Differential Clock Buffer characteristics

Symbol	Minimum	Maximum
R_O	3000Ω	N/A
R_{OS}	unspecified	unspecified
V_{OUT}	N/A	850mV

Current Accuracy

Symbol	Conditions	Configuration	Load	Min.	Max.
I_{OUT}	$V_{DD} = 3.30 \pm 5\%$	$R_{REF} = 475\Omega$ 1% $I_{REF} = 2.32mA$	Nominal test load for given configuration	-12% $I_{NOMINAL}$	+12% $I_{NOMINAL}$

Note:
1. $I_{NOMINAL}$ refers to the expected current based on the configuration of the device.

Differential Clock Output Current

Board Target Trace/Term Z	Reference R, Iref = V_{DD}/(3xRr)	Output Current	V_{OH} @ Z
100Ω (100Ω differential ≈ 15% coupling ratio)	$R_{REF} = 475\Omega$ 1%, $I_{REF} = 2.32mA$	$I_{OH} = 6 \times I_{REF}$	0.7V @ 50

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Absolute Maximum Ratings (Over operating free-air temperature range)

Symbol	Parameters	Min.	Max.	Units
V_{DD_A}	3.3V Core Supply Voltage	-0.5	4.6	V
V_{DD}	3.3V I/O Supply Voltage	-0.5	4.6	
V_{IH}	Input High Voltage		4.6	
V_{IL}	Input Low Voltage	-0.5		
Ts	Storage Temperature	-65	150	°C
V_{ESD}	ESD Protection	2000		V
T_J	Junction Temperature		125	°C

Note:
1. Stress beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device.

DC Electrical Characteristics (V_{DD} = 3.3±5%, V_{DD_A} = 3.3±5%)

Symbol	Parameters	Condition	Min.	Max.	Units
V_{DD_A}	3.3V Core Supply Voltage		3.135	3.465	V
V_{DD}	3.3V I/O Supply Voltage		3.135	3.465	
V_{IH}	3.3V Input High Voltage	V_{DD}	2.0	V_{DD} + 0.3	
V_{IL}	3.3V Input Low Voltage		V_{SS} – 0.3	0.8	
I_{IK}	Input Leakage Current	$0 < V_{IN} < V_{DD}$	-5	+5	µA
V_{OH}	3.3V Output High Voltage	I_{OH} = -1mA	2.4		V
V_{OL}	3.3V Output Low Voltage	I_{OL} = 1mA		0.4	
I_{OH}	Output High Current	I_{OH} = 6 x I_{REF}, I_{REF} = 2.32mA	12.2	15.6	mA
C_{IN}	Input Pin Capacitance		3	5	pF
C_{OUT}	Output Pin Capacitance			6	
L_{PIN}	Pin Inductance			7	nH
I_{DD}	Power Supply Current	V_{DD} = 3.465V, F_{CPU} = 200MHz		200	mA
I_{SS}	Power Down Current	Driven outputs		40	
I_{SS}	Power Down Current	Tristate outputs		12	
T_A	Ambient Temperature		0	70	°C

AC Switching Characteristics ($V_{DD} = 3.3 \pm 5\%$, $V_{DD\_A} = 3.3 \pm 5\%$)

| Symbol	Parameters	Min.	Max.	Units	Notes
T_{rise} / T_{fall}	Rise and Fall Time (measured between 0.175V to 0.525V)	175	700	ps	2
ΔT_{rise} / ΔT_{fall}	Rise and Fall Time Variation		125	ps	2
	Rise/Fall Matching		20	%	2
T_{pd}	PLL Mode		±250	ps	
	Non-PLL Mode	2.5	6.5	ns	
T_{skew}	Output-to-Output Skew		50	ps	3
T_{jitter}	Cycle – Cycle Jitter		50	ps	3, 4
V_{HIGH}	Voltage High including overshoot	660	1150	mV	2
V_{LOW}	Voltage Low including undershoot	-300		mV	2
V_{cross}	Absolute crossing point voltages	250	550	mV	2
ΔV_{cross}	Total Variation of Vcross over all edges		140	mV	2
T_{DC}	Duty Cycle	45	55	%	3

Notes:
1. Test configuration is $R_s = 33.2\Omega$, Rp = 49.9Ω, and 2pF.
2. Measurement taken from Single Ended waveform.
3. Measurement taken from Differential waveform.
4. Measurement taken using M1 data capture analysis tool.

Configuration Test Load Board Termination
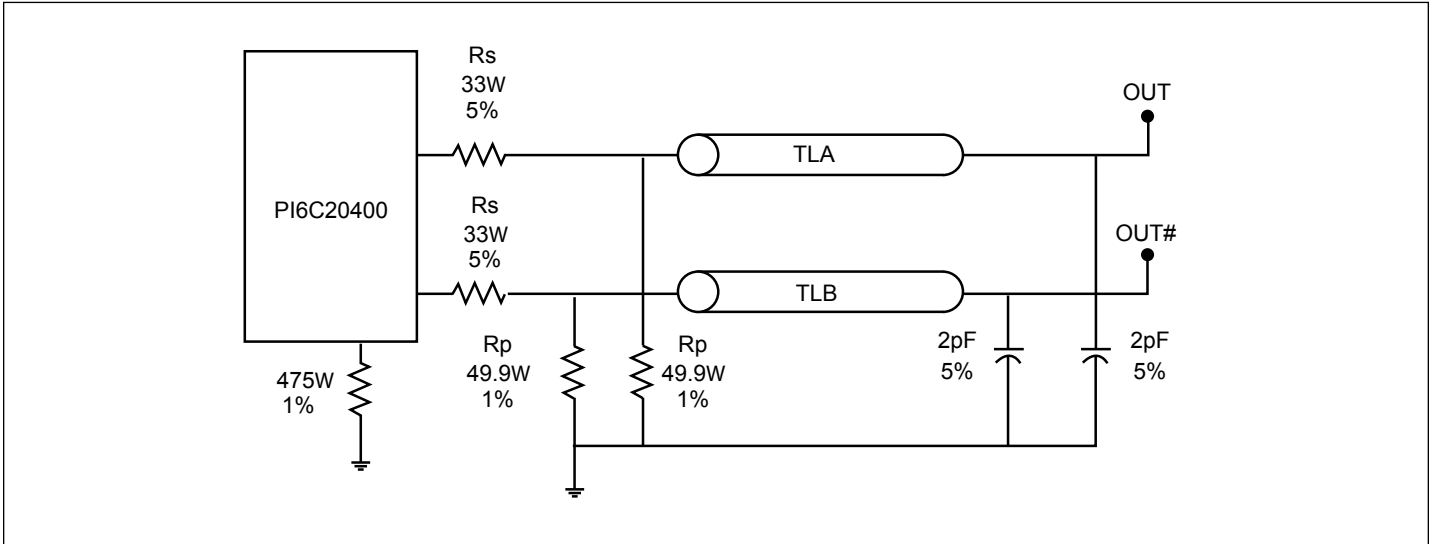
Part Marking
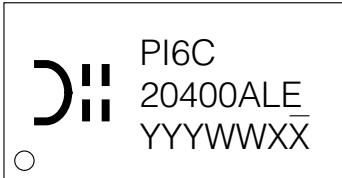
Y: Die Rev
YY: Year
WW: Workweek
1st X: Assembly Code
2nd X: Fab Code

Packaging Mechanical: 28-TSSOP (L)

SYMBOLS	MIN.	NOM.	MAX.
A	–	–	1.20
A1	0.05	–	0.15
A2	0.80	1.00	1.05
b	0.19	–	0.30
c	0.09	–	0.20
D	9.60	9.70	9.80
E1	4.30	4.40	4.50
E	6.20	6.40	6.60
e	0.65 BSC		
L1	1.00 REF		
L	0.45	0.60	0.75
S	0.20	–	–
θ	0°	–	8°

PERICOM®
Enabling Serial Connectivity

DATE: 03/31/16

DESCRIPTION: 28-Pin, 173mil Wide TSSOP

PACKAGE CODE: L (L28)

DOCUMENT CONTROL #: PD-1313   REVISION: F

NOTES:
1. ALL DIMENSIONS IN MILLIMETERS. ANGLES IN DEGREES.
2. JEDEC MO−153F
3. DIMENSIONS DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

16-0076

For latest package info.

please check: http://www.diodes.com/design/support/packaging/pericom-packaging/packaging-mechanicals-and-thermal-characteristics/

Ordering Information

Ordering Code	Package Code	Package Description
PI6C20400LEX	L	28-pin, 173-mil wide (TSSOP)

Notes:

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. E = Pb-free and Green
5. X suffix = Tape/Reel

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PI6C20400

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